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Electronic Version v1.1

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Title of Invention	Bond Pad Structure Comprising Multiple Bond Pads with metal Overlap
Application Number :	09/927675
Date :	2001-08-10
First Named Applican	Perry Guy
Confirmation Number	6524
Attorney Docket Num	er: MTI-31471

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Documents being submitted:	Files	
us-fee-sheet	MTI-31471-usfees.xml	
	us-fee-sheet.xsl	
	us-fee-sheet.dtd	
us-ids	MTI-31471-usidst.xml	
	us-ids.dtd	
	us-ids.xsl	
Comments		